



**Advanced Power
Electronics Corp.**

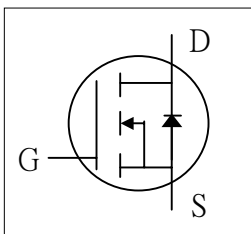
AP09N70I-A

Pb Free Plating Product

N-CHANNEL ENHANCEMENT MODE

POWER MOSFET

- ▼ Dynamic dv/dt Rating
- ▼ Repetitive Avalanche Rated
- ▼ Fast Switching
- ▼ Simple Drive Requirement
- ▼ RoHS Compliant

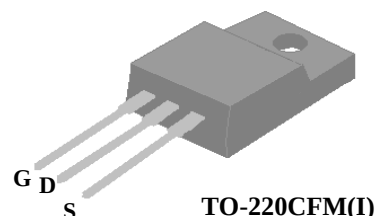


BV_{DSS}	650V
$R_{DS(ON)}$	0.75Ω
I_D	9A

Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220CFM isolation package is universally preferred for all commercial-industrial through hole applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	9	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	5	A
I_{DM}	Pulsed Drain Current ¹	40	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	42	W
	Linear Derating Factor	0.34	W/ $^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy ²	305	mJ
I_{AR}	Avalanche Current	9	A
E_{AR}	Repetitive Avalanche Energy	9	mJ
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Thermal Resistance Junction-case Max.	3	$^\circ\text{C}/\text{W}$
Rthj-a	Thermal Resistance Junction-ambient Max.	65	$^\circ\text{C}/\text{W}$

Data & specifications subject to change without notice

200711051-1/4

Electrical Characteristics@T_J=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	650	-	-	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.6	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =4.5A	-	-	0.75	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	-	4	V
g _{fs}	Forward Transconductance	V _{DS} =50V, I _D =4.5A	-	4.5	-	S
I _{DSS}	Drain-Source Leakage Current (T _J =25°C)	V _{DS} =600V, V _{GS} =0V	-	-	10	uA
	Drain-Source Leakage Current (T _J =150°C)	V _{DS} =480V, V _{GS} =0V	-	-	100	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±30V	-	-	±100	nA
Q _g	Total Gate Charge ³	I _D =9A	-	44	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =480V	-	11	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	12	-	nC
t _{d(on)}	Turn-on Delay Time ³	V _{DD} =300V	-	19	-	ns
t _r	Rise Time	I _D =9A	-	21	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =10Ω, V _{GS} =10V	-	56	-	ns
t _f	Fall Time	R _D =34Ω	-	24	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	2660	-	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	170	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	10	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I _S	Continuous Source Current (Body Diode)	V _D =V _G =0V, V _S =1.5V	-	-	9	A
I _{SM}	Pulsed Source Current (Body Diode) ¹		-	-	40	A
V _{SD}	Forward On Voltage ³	T _J =25°C, I _S =9A, V _{GS} =0V	-	-	1.5	V

Notes:

- 1.Pulse width limited by safe operating area.
- 2.Starting T_J=25°C, V_{DD}=50V, L=6.8mH, R_G=25Ω, I_{AS}=9A.
- 3.Pulse width ≤300us, duty cycle ≤2%.

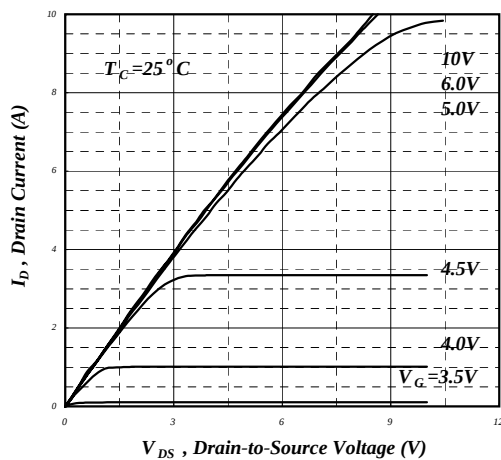


Fig 1. Typical Output Characteristics

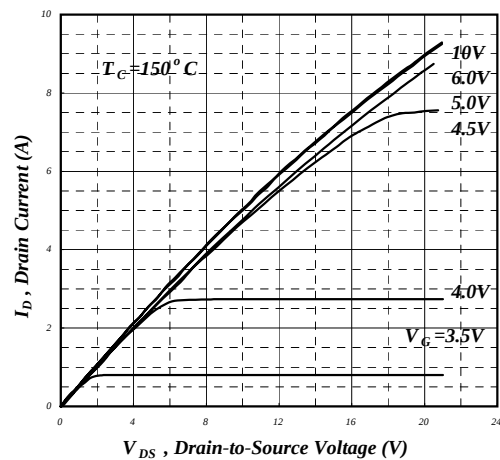


Fig 2. Typical Output Characteristics

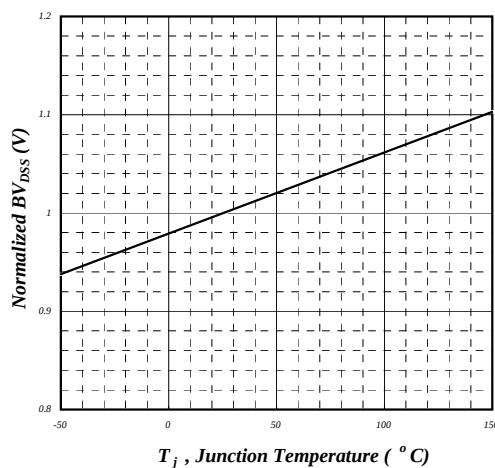


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

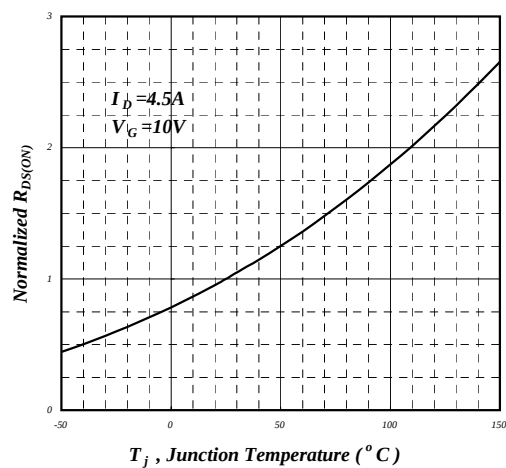


Fig 4. Normalized On-Resistance v.s. Junction Temperature

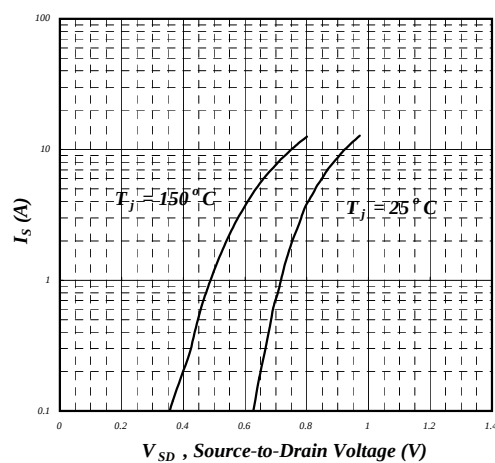


Fig 5. Forward Characteristic of Reverse Diode

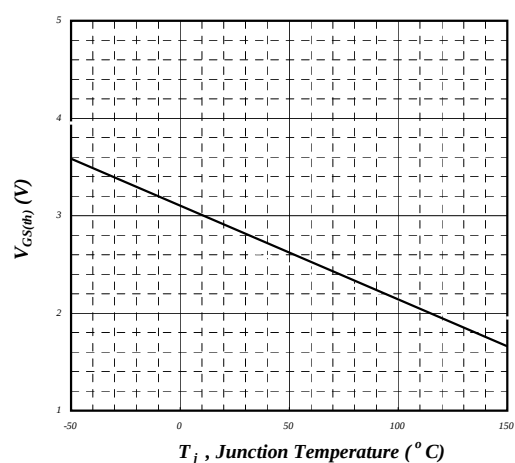


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

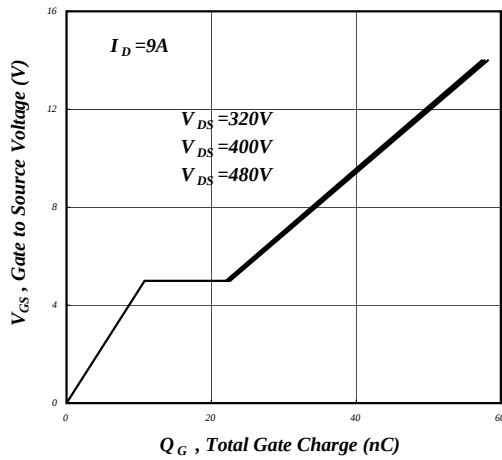


Fig 7. Gate Charge Characteristics

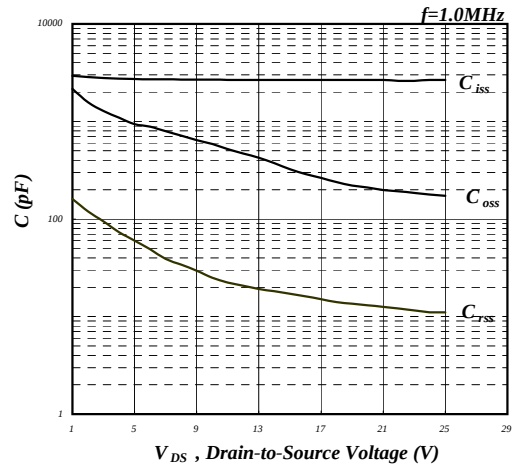


Fig 8. Typical Capacitance Characteristics

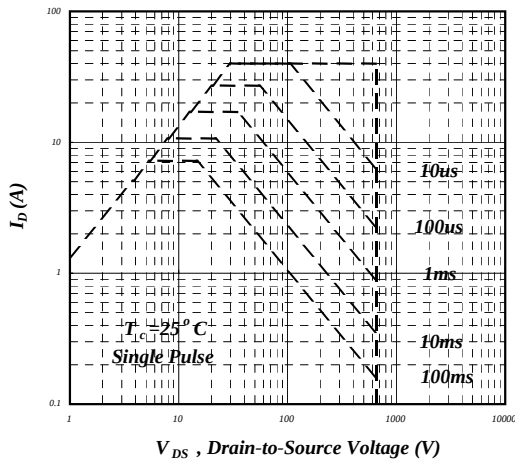


Fig 9. Maximum Safe Operating Area

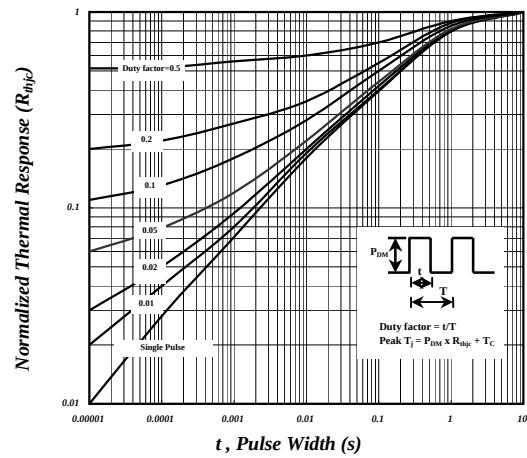


Fig 10. Effective Transient Thermal Impedance

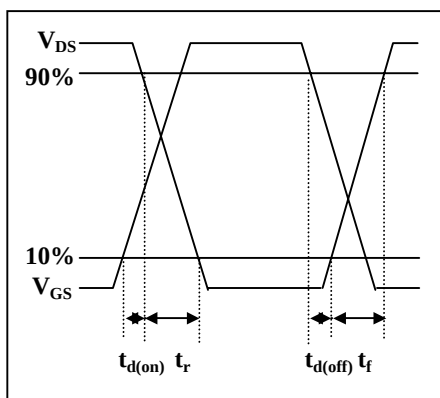


Fig 11. Switching Time Waveform

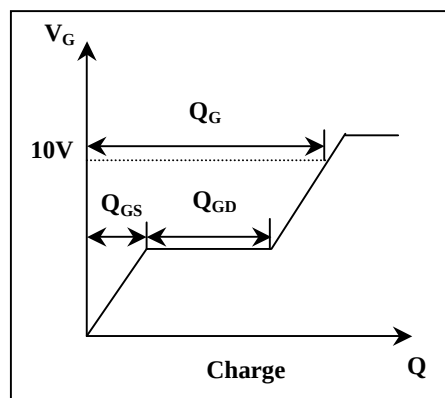


Fig 12. Gate Charge Waveform